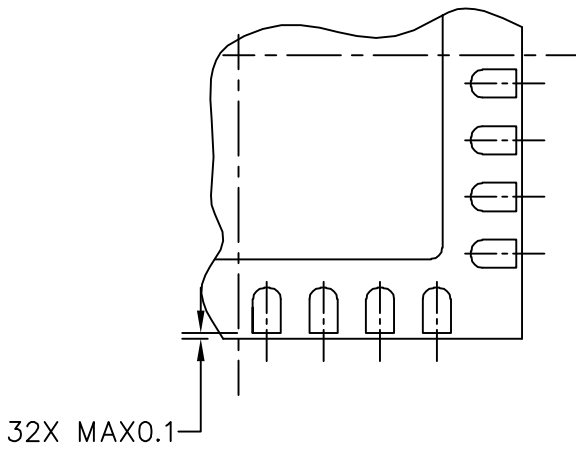
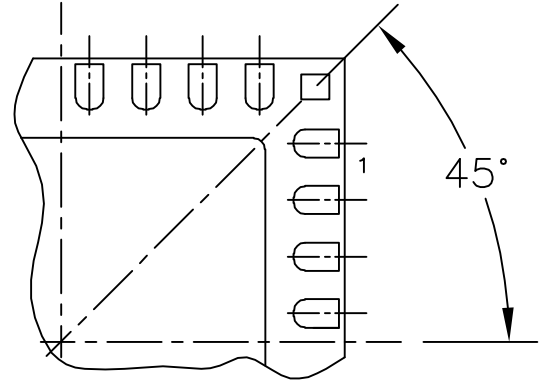


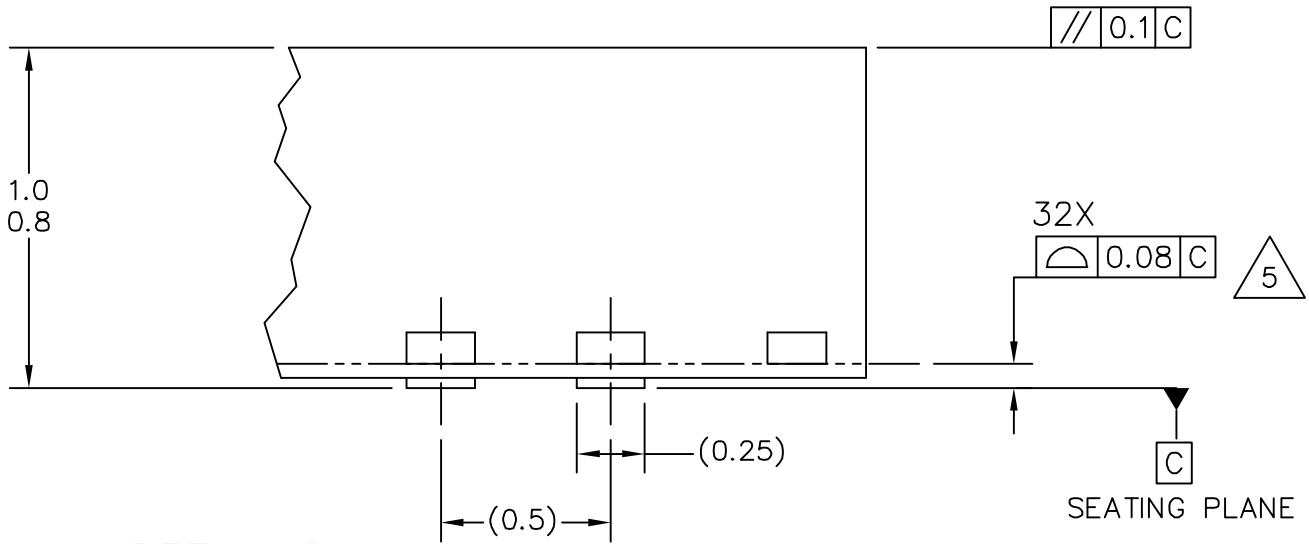
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<b>TITLE:</b> THERMALLY ENHANCED QUAD FLAT NON-LEADED PACKAGE (QFN) 32 TERMINAL, 0.5 PITCH (5 X 5 X 1) 3.6 X 3.6 EP, CASE OUTLINE	DOCUMENT NO: 98ASA10656D	REV: B
	STANDARD: JEDEC MO-220 VHHD-4	
	SOT617-21	11 MAR 2016



DETAIL N



DETAIL M



DETAIL G  
VIEW ROTATED 90° CW

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		STANDARD: JEDEC MO-220 VHHD-4	
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NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. THE COMPLETE JEDEC DESIGNATOR FOR THIS PACKAGE IS: HF-PQFP.
4. RADIUS ON TERMINAL IS OPTIONAL.
- △ 5. COPLANARITY APPLIES TO LEADS, CORNER LEADS, AND DIE ATTACH PAD.
6. FOR ANVIL SINGULATED QFN PACKAGES, MAXIMUM DRAFT ANGLE IS 12°.
7. MINIMUM METAL GAP SHOULD BE 0.2 MM.

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